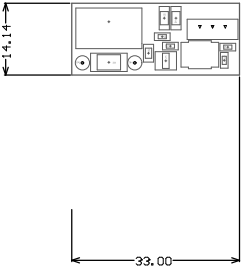


DATE	REV	ENGINEER	COMMENT
*	*	*	INITIAL RELEASE
*	*	*	*
*	*	*	*
*	*	*	*
*	*	*	*


1. FINISH: HASL
2. SOLDERMASK: LPI WHITE
3. SILKSCREEN: BLACK
4. 6MIL TRACE/6MIL SPACE
5. ELECTRICAL TEST

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	25.00mil	4.2	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

1. LEAD-FREE SOLDER
2. IPC-A-610 CLASS 2 ASSEMBLY
3. COMPONENTS ON TOP SIDE ONLY



Symbol	Count	Hole Size	Plated	Hole Type
○	2	40.16mil (1.020mm)	PTH	Round
▽	3	39.37mil (1.000mm)	PTH	Round
	5 Total			

 DeepFlight 1150 Brickyard Cove Rd, #102 Richmond, CA 94801	ENGINEER: E. CHIU	TITLE: PCB TITLE	
	PCB DESIGNER: E. CHIU		
	DATE: 11/29/2020	PART NO: PCB PN	REV: *
	FILE NAME: PAPR1ka PCB.PcbDoc	DWG NO:	SCALE: